

SOT2086-2

HVQFN116 thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

17 November 2023

Package information



1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN116
Package style descriptive code	HVQFN (thermal enhanced very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	27-04-2023
Manufacturer package code	98ASA01830D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	8.9	9	9.1	mm
package width	8.9	9	9.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm



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2 Package outline

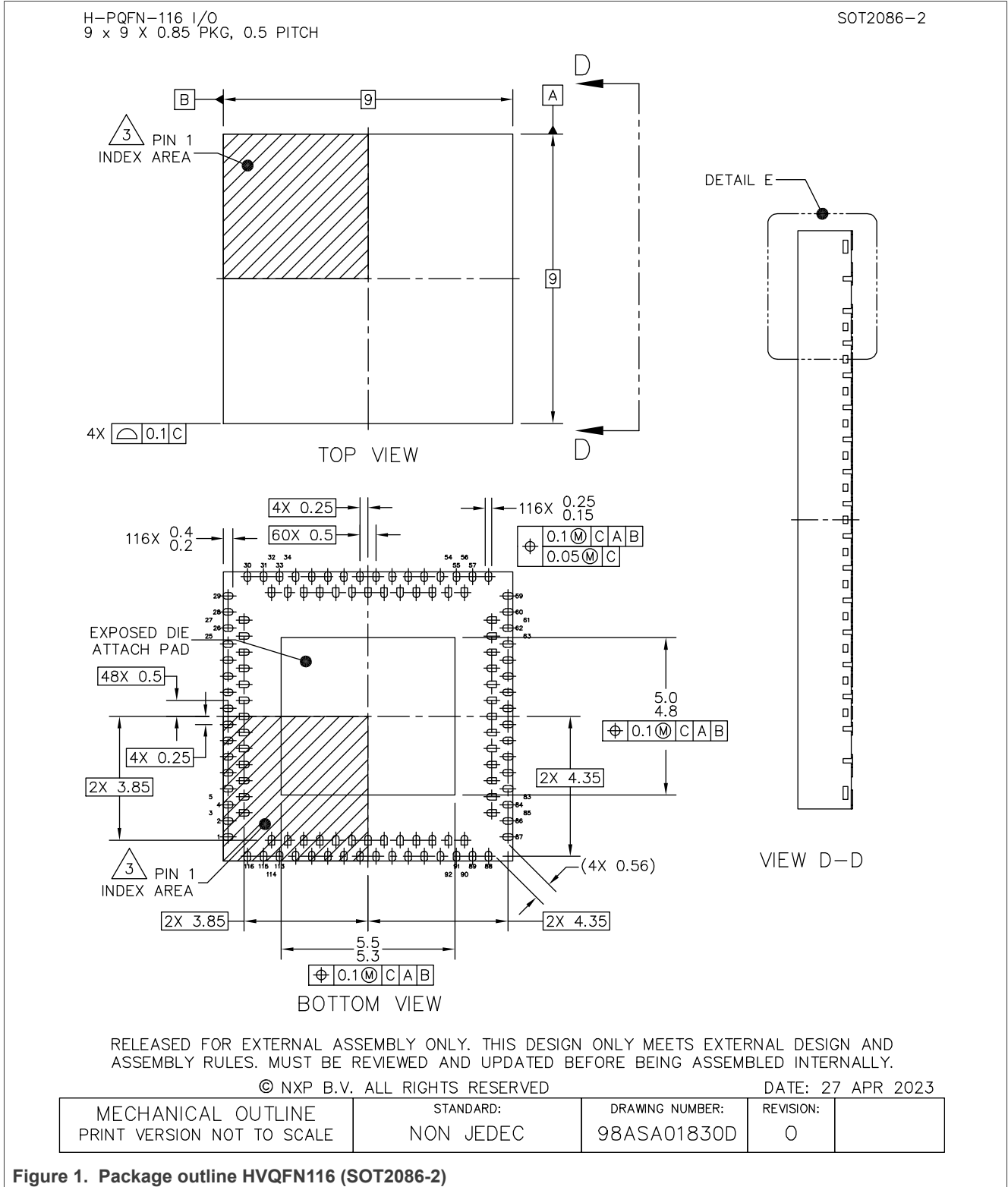


Figure 1. Package outline HVQFN116 (SOT2086-2)

HVQFN116 thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

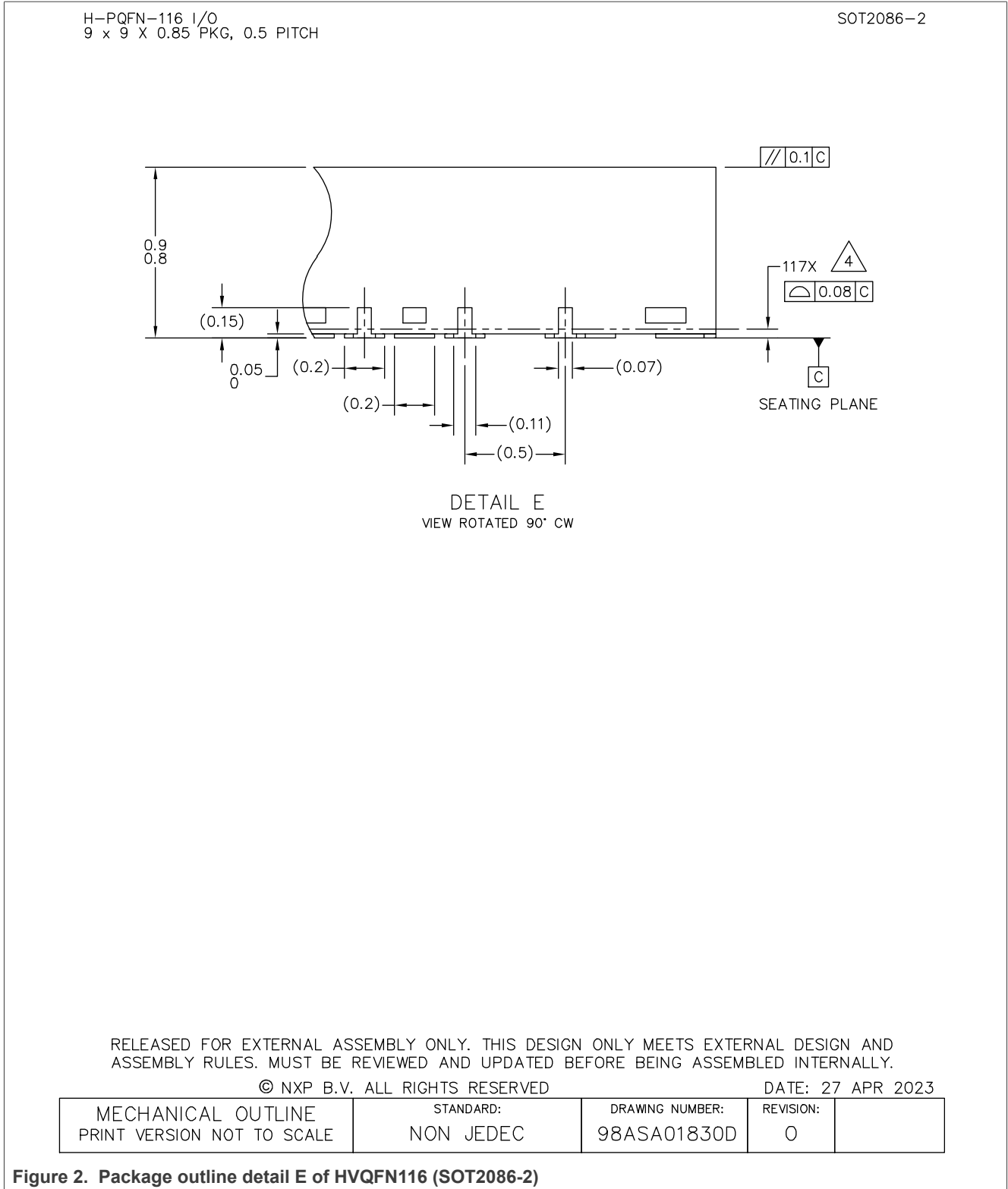


Figure 2. Package outline detail E of HVQFN116 (SOT2086-2)

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3 Soldering

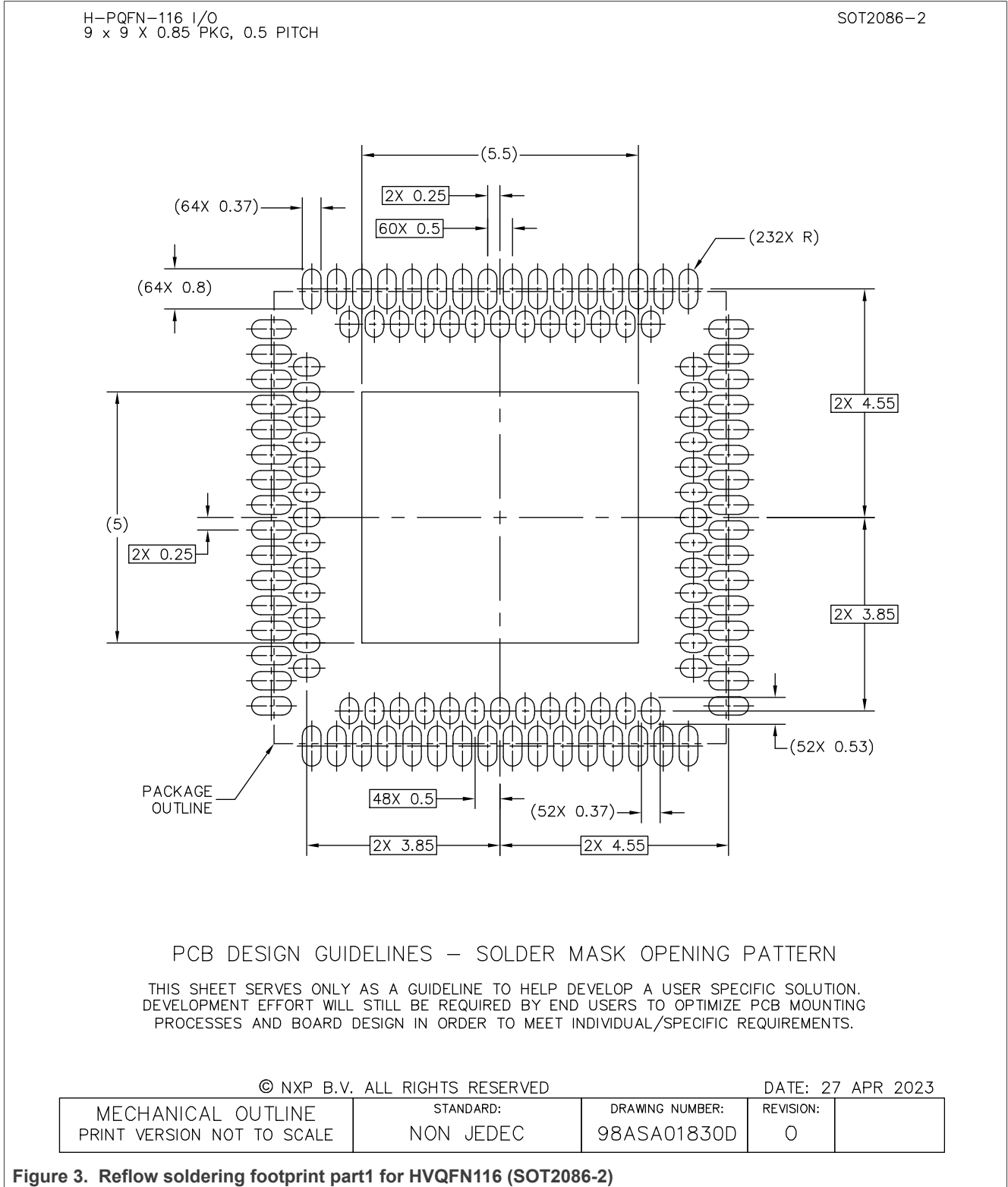


Figure 3. Reflow soldering footprint part1 for HVQFN116 (SOT2086-2)

HVQFN116 thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

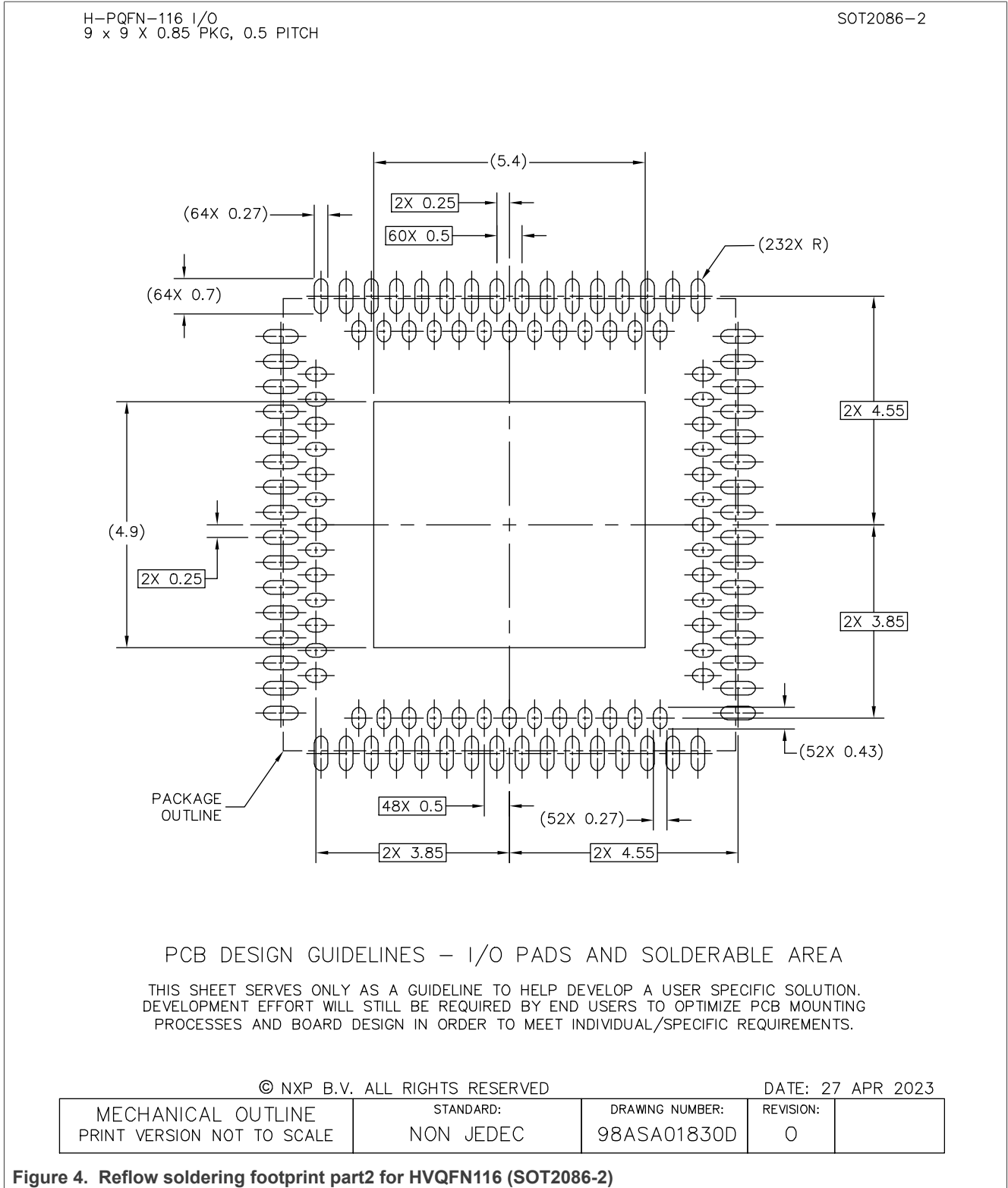


Figure 4. Reflow soldering footprint part2 for HVQFN116 (SOT2086-2)

HVQFN116 thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

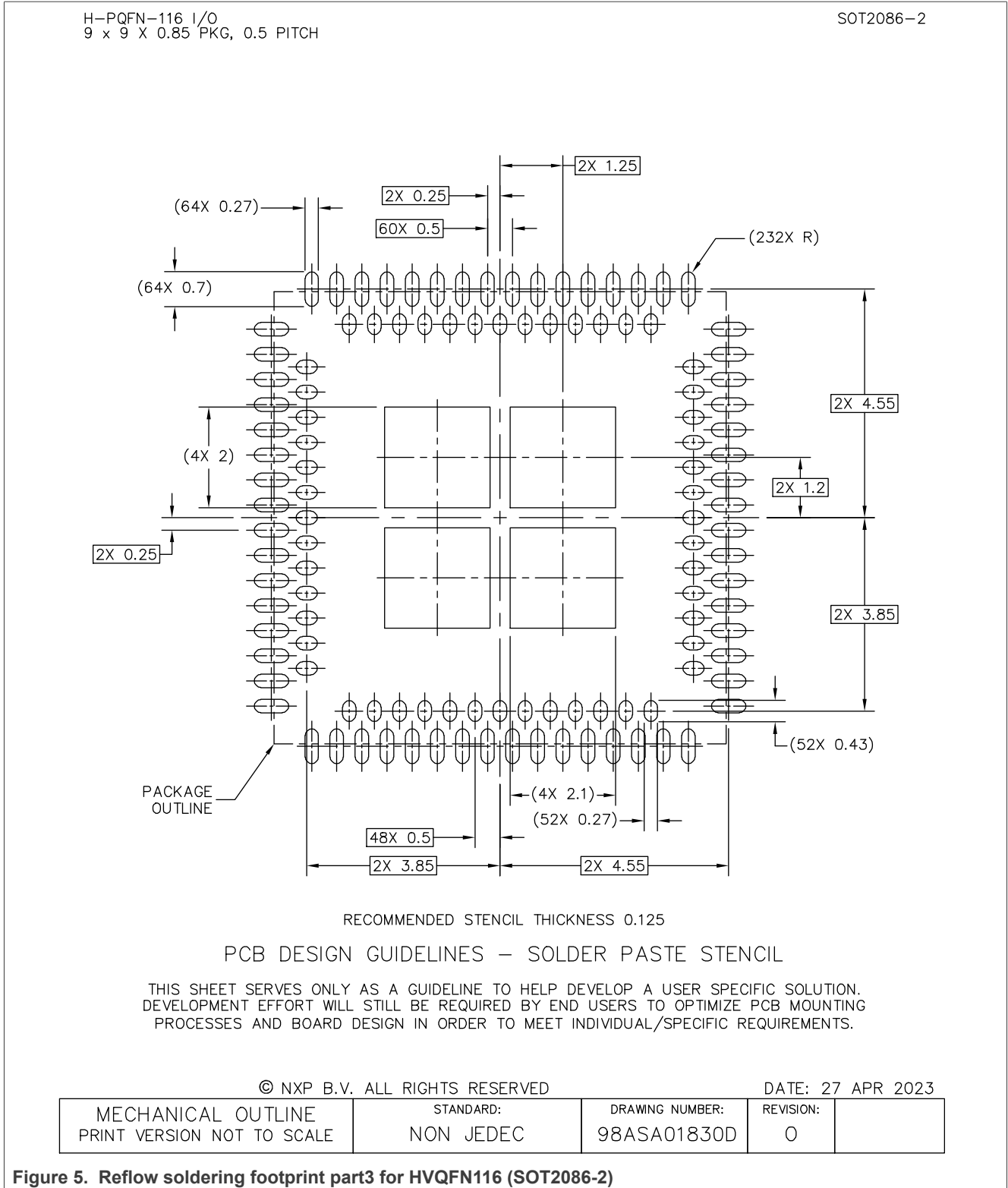


Figure 5. Reflow soldering footprint part3 for HVQFN116 (SOT2086-2)

HVQFN116 thermal enhanced very thin quad flat package, no leads, 116 terminals, 0.5 mm pitch, 9 mm x 9 mm x 0.85 mm body

H-PQFN-116 I/O
9 x 9 X 0.85 PKG, 0.5 PITCH

SOT2086-2

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS AND DIE ATTACH PAD.
5. MIN. METAL GAP FOR LEAD TO EXPOSED PAD SHALL BE 0.2 MM.

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DATE: 27 APR 2023

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01830D	REVISION: 0	
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Figure 6. Package outline note HVQFN116 (SOT2086-2)

4 Legal information

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